



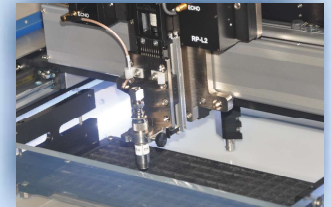
VUE 250-P

SCANNING ACOUSTIC MICROSCOPE

Semiconductor Package Failure Analysis
voids · disbonds · cracks · delamination · internal defects

Included Software Modes:

- Basic (user friendly)
- Advanced (detailed analysis)
- Production (automated scanning)
- Offline Analysis (virtual scanning)



info@okos.com

Customer Interface

Dual 22" HD LED Monitors

Fixtures

Tray Fixture
Optional Through
Transmission Bracket
LED illumination

Instrumentation

Digital Pulser Receiver
Up to 4 GHz Digitizer

Scan Area

Partial JEDEC Tray

Maintenance Free Scan Axis

Motor: Linear Servo
Max Velocity: 500 mm/s
Accuracy & Repeatability: +/- 1.0 micron

Scan Envelope:

250 mm

Low Maintenance Step Axis:

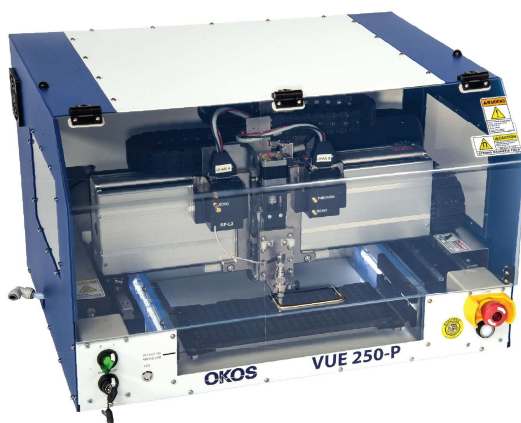
Step Envelope 150 mm

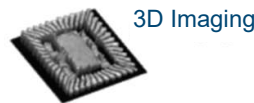
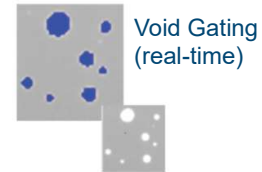
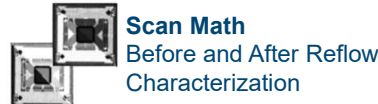
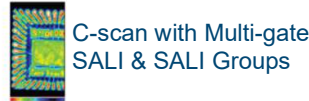
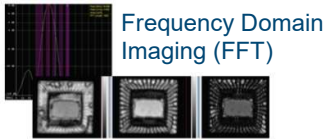
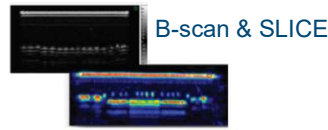
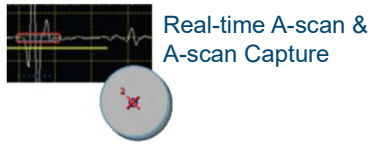
Low Maintenance Focus Axis:

Focus Envelope 35 mm

Dimensions:

0.64 m x 0.61 m x 0.5 m (WDH)
52 kg





OKOS Digital Imaging System (ODIS)



VUE 250-P imaging power surpasses modern standards delivering premium FA Lab features to semiconductor fabrication facilities. ODIS is the latest Acoustic Microscopy software with rich technical content built on current platforms and industry feedback. It includes both time domain and frequency domain imaging in real-time. Advanced analysis is provided through quantitative tools for measurement and classification of parts.

The Analysis version of ODIS allows non-scanning computers to virtually scan, view, and analyze data for simultaneous real-time analysis or post collection review. Previously undetected flaws can now be imaged with poled peak analysis. Supplied with your choice of Windows 7 or 10.

- Counterfeit Detection
- Product Inspection
- Product Reliability
- Quality Control
- Process Validation
- Failure Analysis
- Vendor Qualification
- R&D

Application Specific Transducers

for the highest quality resolution.

Multiple transducer design for enhanced scan capability.

